

FULL ADDITIVE PROCESS WITH FILLED PLATED THROUGH HOLES

ABSTRACT

5 A method provides for additive plating on a subcomposite
having filled plated through holes. Fine-line circuitry is
achieved via electroless deposition onto a dielectric substrate
after the through hole is plated and filled. Fine-line circuitry
may be routed over landless, plated through holes thereby
increasing the aspect ratio and the available surface area for
10 additional components and wiring.